

ABSTRACT OF THE DISCLOSURE

In this invention, SO-RIMM sockets are arranged on a mother board so that an output side terminal of a connector provided on a preceding-stage SO-RIMM and an input side terminal of a connector provided on a succeeding-stage SO-RIMM will be set to face each other at a close distance. Therefore, in a high-speed memory device constructed by connecting a plurality of flat high-speed memory modules each including a connector on one side of which input side and output side terminals for dealing with a high-speed signal of plural-bit width whose impedance is controlled and which is transmitted from a memory controller to a terminal resistor are arranged, a high-speed memory device in which high-speed memory modules can be cascade-connected and which can maintain the impedance of a memory bus signal in a constant value by use of an inexpensive multi-layered circuit board structure, a socket mounting structure of the high-speed memory device and a mounting method of the high-speed memory device can be provided.